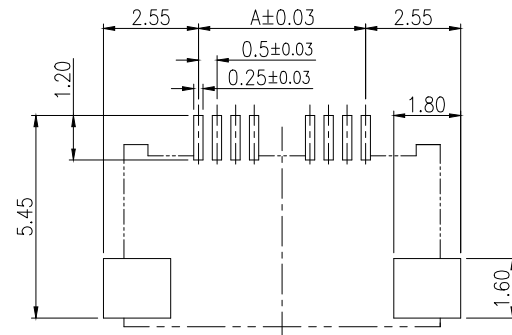
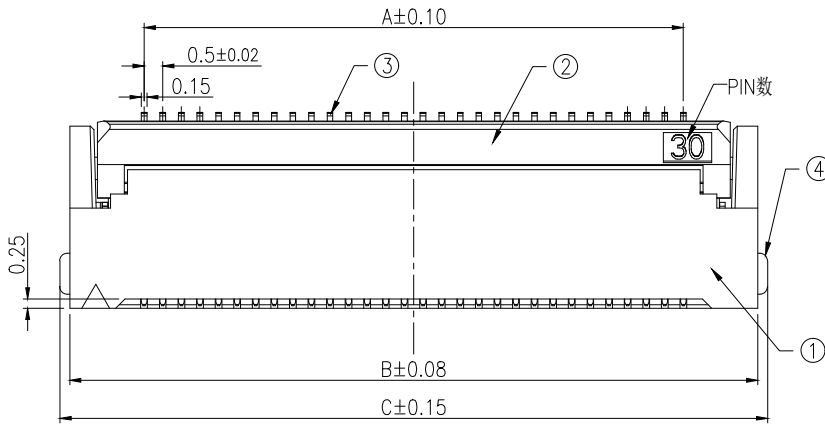


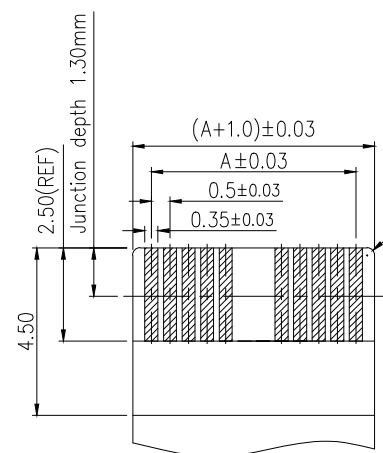
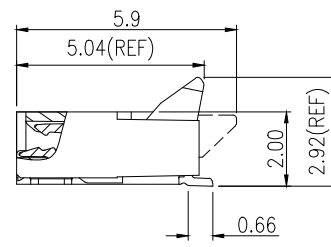
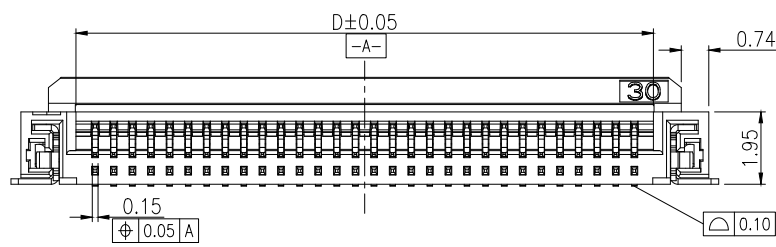
REV.	ECN NO.	LOCAS.	DESCRIPTION	DATE	DESIGN
A			NEW DRAWING		



RECOMMENDED PCB LAYOUT

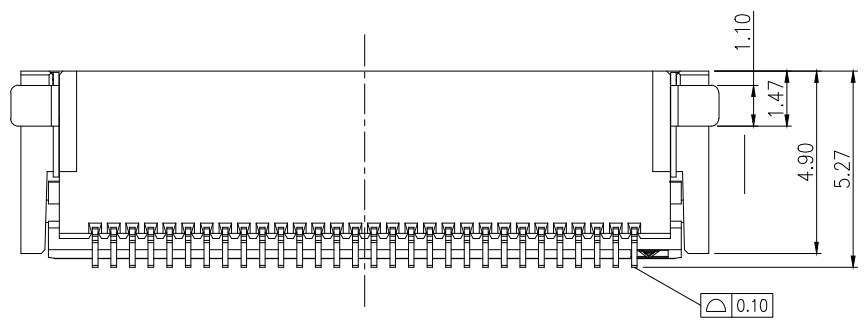
NOTES:

- HUOSING: LCP HIGH-TEMP THERMOPLASTIC UL94V-0 COLOR:NATURE
- ACTUATOR: PA9T HIGH-TEMP THERMOPLASTIC UL94V-0 COLOR:BLACK
- TERMINAL: PHOSPHOR BRONZE  
 PLATING: CONTACT AREA: 1 μ" GOLD PLATING ON CONTACT AREA  
 50~100u" NICKEL UNDER PLATING OVER ALL.  
 PLATING: SOLDER AREA: GOLD FLASH ON SOLDER AREA  
 50~100u" NICKEL UNDER PLATING OVER ALL.
- FITTING NAIL: BRASS  
 PLATING: 100~150 μ" MATTE-TIN (LEAD FREE)  
 PLATING: OVERALL 50~100 μ" NICKEL UNDER PLATED.
- SPECIFICATION: OVERALL 50V AC/DC  
 CURRENT RATING: 0.5A 50V AC/DC  
 CONTACT RESISTANCE: 30mΩ MAX  
 INSULATION RESISTANCE: 500MΩ AT 250V DC  
 WITHSTANDING VOLTAGE: 500V AC/minute  
 OPERATING TEMPERATURE RANGE: -25° C~+85° C



APPLICABLE FPC/FFC  
 T=0.30<sup>+0.02</sup><sub>-0.01</sub>

NO.	DIM positions	A	B	C	D
5		2.00	6.00	6.55	3.05
6		2.50	6.50	7.05	3.55
8		3.50	7.50	8.05	4.55
9		4.00	8.00	8.55	5.05
10		4.50	8.50	9.05	5.55
12		5.50	9.50	10.05	6.55
13		6.00	10.00	10.55	7.05
14		6.50	10.50	11.05	7.55
15		7.00	11.00	11.55	8.05
16		7.50	11.50	12.05	8.55
18		8.50	12.50	13.05	9.55
20		9.50	13.50	14.05	10.55
24		11.50	15.50	16.05	12.55
25		12.00	16.00	16.55	13.05
28		13.50	17.50	18.05	14.55
30		14.50	18.50	19.05	15.55
32		15.50	19.50	20.05	16.55
34		16.50	20.50	21.05	17.55
36		17.50	21.50	22.05	18.55
40		19.50	23.50	24.05	20.55
45		22.00	26.00	26.55	23.05
50		24.50	28.50	29.05	25.55
54		26.50	30.50	31.05	27.55
60		29.50	33.50	34.05	30.55
68		33.50	37.50	38.05	34.55
80		39.50	43.50	44.05	40.55
96		47.50	51.50	52.05	48.55



DESIGN:		易芯精密科技(浙江)有限公司 Easychips Precision Technology (Zhejiang) Co., Ltd.				
CHECK:						
APPROVED:						
DIM	TOL	DIM	TOL	TITLE:	(0.5前插后掀盖H2.0欧姆龙款)	
X.	±0.25	X°	±3.0°	PART NO.	EC-0520D-GX-nPWB	
X.X	±0.20	X.X°		REV.	A	SCALE: N/A
X.XX	±0.15	X.XX°		UNIT:	mm	SHEET: 1/1
X.XXX		X.XXX°				